2024 AP-ALD Technical Sessions Overview					
Sheraton Shanghai Waigaoqiao Hotel, Shanghai, China, Oct. 17 ~ Oct. 20, 2024					
Date	Time	Meeting room A	Meeting room B	Meeting room C	
	9:00-9:10	Opening (Shanghai Ballroom)			
	9:10-10:40	Plenary Session (Shanghai Ballroom)			
	11:00-12:10	Sp	Special Keynote (Shanghai Ballroom)		
Oct 18th	14.00 15.25	Session A1	Session B1	Session C1	
000 1000	14.00-13.23	ALD Oxides I	ALD Simulations I	ALD Catalysis I	
	15.50 17.15	Session A2	Session B2	Session C2	
	13.30-17.13	ALD Oxides II	ALD Simulations II	ALD Catalysis II	
	17:15-18:30	Poster	Session I (Shanghai Ballroor	n Anteroom)	
	0.00.10.25	Session A3	Session B3	Session C3	
	9.00-10.23	ALD Oxides III	Area Selective ALD I	ALD Energy I	
	10:50-12:15	Session A4	Session B4	Session C4	
		ALD 2D Materials	Area Selective ALD I	ALD Energy II	
Oct 19th	14:00-15:25	Session A5 ALD Memory I	Session B5 ALD Novel Process and Instrument I	Session C5 ALD Membrane	
	15:50-17:25	Session A6 ALD Memory II	Session B6	Session C6	
			ALD Novel Process and	ALD Emerging	
			Instrument II	Applications	
Oct 20th	9:00-9:55	Session A7 ALD TFT I	ALD Display	Conference Committee	
	9:55-11:00	Session A8 ALD TFT II	Session B7 ALD Encapsulation	Meeting	

	Friday, October 18, 09:00 –09: 10
Opening	Shanghai Ballroom 2

Friday, October 18, 09:10 –10: 40		
Plenary Sess	ion P Shanghai Ballroom 2	
Session Chai	Session Chair: Prof. Rong Chen, Huazhong University of Science and Technology,	
China.		
	ALD for Two Dimensional Chalcogenides Nanomaterials	
09:10-09:55	Prof. Hyungjun Kim	
	School of Electrical and Electronic Engineering, Yonsei University, Korea	
09:55-10:40	Process Technologies to Enable Future Device and Scaling	
	Dr. Yamato Tonegawa	
	Tokyo Electron Technology Solutions Ltd, Japan	

Friday, October 18, 10:40 –12: 10		
Special Keynote S Shanghai Ballroom 2		
Session Chair: Prof. Soo-Hyun Kim, Ulsan National Institute of Science and		
Technology, Korea		
10:40-11:00	Coffee break	
	ALD for Photovoltaics	
11:00-11:35	Dr. Weiming li	
	Jiangsu Leadmicro Nano Technology Co. Ltd. China	
11:35-12:10	Atomic-Layer-Deposited Aluminum Oxide for Metal-Oxide Thin-Film	
	transistors	
	Prof. Man Wong	
	Hongkong University of Science and Technology, Hong Kong, China	

Friday, October 18, 14:00 –15: 25		
Session A1	Meeting room A	
Session Chain	: Prof. Hongliang Lu	
	Challenges of ALD Oxide Semiconductor Channel Materials for Emerging	
	Semiconductor Applications (keynote)	
14:00-14:30	Prof. Jin-Seong Park	
	Division of Material Science and Engineering, Hanyang University, Seoul, 04763	
	Republic of Korea	
14:30-14:50	Oxide Semiconductors for Advanced DRAM Applications (invited)	
	Prof. Yanqing Wu	
	Division of Material Science and Engineering, Hanyang University, Seoul, 04763	
	Republic of Korea	

	Atomic Layer Deposition of Amorphous and Crystalline Oxide
	Semiconductors and Their Device Applications (invited)
14:50-15:10	Prof. Takanori Takahashi
	Graduate School of Science and Technology, Nara Institute of Science and
	Technology, Ikoma, Nara, 630-0192
15:10-15:25	Atomic-Layer-Deposited Oxide Semiconductor Thin-Film Transistors for
	Monolithic 3D Integration
	Jinxiong Li ¹ , Shanshan Ju ¹ , Jiye Li ² , Yuqing Zhang ³ , Songjie Yang ¹ , Xu Tian ¹ , Lei
	Lu ² , Shengdong Zhang ² , and Xinwei Wang ^{1,*}
	School of Advanced Materials, Peking University, Shenzhen 518055, China

Friday, October 18, 14:00 –15: 25		
Session B1	Meeting room B	
Session Chair: Prof. Xinwei Wang		
	Precursor design and reaction mechanism of atomic layer deposition	
	(invited)	
14:00-14:20	Guoyong Fang	
	College of Chemistry and Materials Engineering, Wenzhou University, 325035,	
	China	
	The advantages and applications of UHV-ALD (keynote)	
14:20-14:50	Sunan Ding	
	School of Integrated Circuits, Nanjing University Suzhou/Jiangsu/China, 215613	
	Physical and chemical properties of ALD precursors, from a structural	
14.50 15.10	perspective (invited)	
14.30-13.10	Xiabing Lou	
	Shanghai Oriphant Chemicals Co., Ltd., Shanghai, China, 201500	
15:10-15:25	Modeling Conformality of Silicon Nitride in High Aspect Ratio Trench	
	Structure by Atomic Layer Deposition	
	Sen Deng1, Hua Shao2*, Rui Chen 2*, Dandan Han1, Yayi Wei1,2*	
	School of Integrated Circuits, University of Chinese Academy of Sciences, Beijing,	
	China, 100049	

	Friday, October 18, 14:00 –15: 25	
Session C1	Meeting room C	
Session Chair: Prof. Yong Qin		
	Development of Catalytic Materials by Atomic Layer Deposition and its	
	Application for Renewable Energy (invited)	
14:00-14:20	Woo-Jae Lee	
	School of Nanotechnology and Semiconductor Engineering, Pukyong National	
	University, Korea, 48513	

14:20-14:40	Precise metal location control and dynamic catalysis (invited)
	Bin Zhang
	State Key Laboratory of Coal Conversion, Institute of Coal Chemistry, Chinese
	Academy of Sciences, Taiyuan, China, 030001
	Spatially confined alloying of Pt accelerates mass transport for fuel cell
	oxygen reduction
14:40-14:55	Yuxin Gao, Hang Liu, Xiao Liu*, Bin Shan*, Rong Chen
	School of Materials Science and Engineering, Huazhong University of Science and
	Technology, Wuhan 430074, Hubei, People's Republic of China
	Atom-by-atom Synthesis of Heterogeneous Catalysts using Atomic Layer
14:55-15:25	Deposition (keynote)
	Junling Lu
	Key Laboratory of Precision and Intelligent Chemistry, School of Chemistry and
	Materials Science, (iChem)University of Science and Technology of China, Hefei,
	Anhui 230026 China

Friday, October 18, 15:50 –17: 15		
Session A2 Meeting room A		
Session Chair: Prof. Jin-Seong Park		
	On the Reliabilities of ALD-based HZO Ferroelectric Memory Capacitors	
	(Keynote)	
15:50-16:20	Jiezhi Chen	
	School of Information Science and Engineering, Shandong University, Qingdao,	
	China	
	Design of Ferroelectric Hf _x Zr _{1-x} O ₂ Thin Films by Atomic Layer Deposition	
	(invited)	
16:20-16:40	Takashi Onaya	
	Department of Advanced Materials Science, The University of Tokyo, 5-1-5	
	Kashiwanoha, Kashiwa, Chiba 277-8561, Japan	
	Metal-oxide Self-rectifying Memristors for In-memory Computing (invited)	
16.40 17.00	Yi Li	
10:40-17:00	School of Integrated Circuits, Huazhong University of Science and Technology,	
	Wuhan, China, 430074	
	HfO ₂ -Based Ferroelectric Thin Films and Memory Device Adopting ALD	
17:00-17:15	Method	
	Jiajia Liao ¹ , Min Liao ^{1*} , and Yichun Zhou ^{1*}	
	School of Advanced Materials and Nanotechnology, Xidian University, Xi'an,	
	Shaanxi, 710126, China	

Friday, October 18, 15:50 –17: 15		
Session B2	Meeting room B	
Session Chair	: Prof. Sunan Ding,	
	Virtual System of ALD: Visualize the Entire Life of Precursors Using	
	Simulation (invited)	
15:50-16:10	Liwei Zhuang	
	School of Chemical Engineering, East China University of Science and Technology,	
	Shanghai 200237, China	
	Multistep Inorganic Synthesis: A Next Step of Chemical Synthesis with	
	ALD (keynote)	
16:10-16:40	Norifusa Satoh	
	Research Center for Macromolecules and Biomaterials, National Institute for	
	Materials Science, Tsukuba, 305-0044	
	Comparative Study of H ₂ O and H ₂ O ₂ Oxidants for SiO ₂ Atomic Layer	
	Deposition Using Tris(dimethylamino) silane: A Computational	
16.40 17.00	Investigation (invited)	
10:40-17:00	Youngho Kang	
	Department of Materials Science and Engineering, Incheon National University,	
	Incheon 22012, Korea	
17:00-17:15	Density Functional Insights Coupled Numerical Nucleation Model for	
	Inherently Selective Atomic Layer Deposition	
	Yanwei Wen ¹ , Yuxiao Lan ¹ , Haojie Li ¹ , Bin Shan ¹ and Rong Chen ^{2,*}	
	School of Materials Science and Engineering, Huazhong University of Science and	
	Technology, Hubei 430074, China	

Friday, October 18, 15:50 –17: 10		
Session C2	Meeting room C	
Session Chair	Session Chair: Prof. Junling Lu	
	Synthesizing atomically dispersed catalysts by Atomic Layer Deposition	
	(invited)	
15:50-16:10	Jiankang Zhang	
	Interdisciplinary Research Center of Biology & Catalysis, School of Life Sciences,	
	Northwestern Polytechnical University, Xi'an 710072, P. R. China	
	ALD ultrathin amorphous TiO ₂ film in a fluidized bed reactor for	
	improving the weatherability of TiO ₂ pigment	
16:10-16:25	Jing Guo, Bingkang Niu, Huifang Lou, Zhengyi Chao, Youzhi Liu	
	Shanxi Province Key Laboratory of Chemical Process Intensification, North	
	University of China, Taiyuan 030051, China	

16.25 16.40	High Crystallinity Yttrium-doped ZrO ₂ under 2 nm through Atomic Layer
	Modulation
	Ngoc Le Trinh ¹ , Bonwook Gu ¹ , Wonjoong Kim ¹ , Byung-ha Kwak ² , Hyun-Mi Kim ³ ,
10.23-10.40	Hyeongkeun Kim ³ , Youngho Kang ¹ , Il-Kwon Oh ² and Han-Bo-Ram Lee ^{1*}
	Department of Materials Science and Engineering, Incheon National University,
	Incheon, Korea
16:40-17:10	Atomic layer deposition of the geometry separated Lewis and Brønsted acid
	sites for cascade catalysis glucose conversion (keynote)
	Jun Huang
	Laboratory for Catalysis Engineering, School of Chemical and Biomolecular
	Engineering, Sydney Nano Institute, the University of Sydney, Sydney, NSW 2006,
	Australia

Saturday, October 19, 9:00 –10: 25	
Session A3	Meeting room A
Session Chair: Prof. Lance Li	
	Improvement of GaN/dielectric interface properties using atomic layer
00.00 00.20	deposition (Keynote)
09.00-09.30	Toshihide Nabatame
	National Institute for Materials Science, Tsukuba, Ibaraki, Japan, 305-0044
	Building a Spiking Sensory Neuron with Oxide-based Neuromorphic
	Devices (invited)
09:30-09:50	Changjin Wan
	School of Electronic Science and Engineering, Nanjing University, Nanjing, Jiangsu
	Province, China, 210023
	Evidence of Oxygen Vacancy Generation as Physical Origin of Endurance
	Fatigue of Si FeFET with TiN/Hf _{0.5} Zr _{0.5} O ₂ /SiO _x /Si Gate Stacks (invited)
09:50-10:10	Xiaolei Wang
	Institute of Microelectronics of the Chinese Academy of Sciences (IMECAS),
	Beijing, 100029, China
Insight into Temperature-dependent Ferroelectric Polarization Switch	
	Characteristics in Ga-Doped HfO ₂ Thin Films
10:10-10:25	Yu-Chun Li ¹ , Zi-Ying Huang ¹ , and Hong-Liang Lu ^{1,*}
	State Key Laboratory of ASIC and System, Shanghai Institute of Intelligent
	Electronics & Systems, School of Microelectronics, Fudan University, Shanghai
	200433, China; Zhangjiang Fudan International Innovation Center, Shanghai
	201203, China; National Integrated Circuit Innovation Center, Shanghai 201203

Saturday, October 19, 9:00 –10: 25	
Session B3	Meeting room B
Session Chair: Prof. Norifusa Satoh	
	A Paste-Like Patterning Resist for Area-Selective ALD (invited)
00.00 00.20	Yanhao Yu
09.00-09.20	Department of Materials Science and Engineering, Southern University of Science
	and Technology, Shenzhen, Guangdong, 518055
	Rediscovery of Atomic Layer Deposition to Overcome the Limitations of
	Semiconductor Manufacturing (keynote)
09:20-09:50	Han-Bo-Ram Lee
	Materials Science & Engineering, Incheon National University, Incheon, Korea,
	22012
	Study on Area-Selective Atomic Layer Deposition of Al ₂ O ₃ with a Series of
00.50 10.10	Al Precursors(invited)
09.30-10.10	Il-Kwon Oh
	Department of Electrical and Computer Engineering, Ajou University, Korea
10:10-10:25	Atomic Layer Deposition of Molybdenum Film using Metal Organic
	Precursors
	Bonwook Gu ¹ , Kieran G Lawford ² , Kwang Yong An ¹ , Seán T. Barry ² , Han-Bo-Ram
	Lee ¹ *
	Department of Materials Science and Engineering, Incheon National University,
	Incheon 22012, Republic of Korea

Saturday, October 19, 9:00 –10: 25	
Session C3	Meeting room C
Session Chair	: Prof. Se Hun Kwon
	Advancements in Surface Engineering through Atomic Layer Deposition
	for Lithium Batteries (invited)
09:00-09:20	Jin Xie
	School of Physical Science and Technology & Shanghai Key Laboratory of
	High-resolution Electron Microscopy, Shanghai Tech University, China
	All-Perovskite Tandem Solar Cells (invited)
00.20 00.40	Dewei Zhao
09:20-09:40	College of Materials Science and Engineering, Sichuan University, Chengdu
	610065, China
09:40-09:55	Highly Durable Pt Based Fuel Cell Catalysts via Atomic Layer Deposition
	Xiao Liu ¹ , Hang Liu ² , Yuxin Gao ² , Bin Shan ² and Rong Chen ¹
	State Key Laboratory of Intelligent manufacturing Equipment and Technology,
	School of Mechanical Science and Engineering, Huazhong University of Science and
	Technology, Wuhan, China, 430074

	Precise Surface Modification of Solid Fuel Particles by Atomic/Molecular
09:55-10:25	Layer Deposition: Enhanced Safety, Stability, and Energy Release
	Performances (keynote)
	Hao Feng
	Xi'an Modern Chemistry Research Institute 168 E. Zhangba Road, Xi'an, Shaanxi,
	China, 710065

	Saturday, October 19, 10:50 –12:15
Session A4	Meeting room A
Session Chair	: Prof. Toshihide Nabatame
	Integration of Single-Crystal High-k Dielectrics with 2D Monolayer
	Transistors (keynote)
10:50-11:20	Lain-Jong Li
	Department of Mechanical Engineering, The University of Hong Kong, Hong Kong,
	China
	Atomic-layer-deposited elemental chalcogen thin films for nanoelectronics
	(invited)
11.20-11.40	Joonki Suh
11.20-11.40	Department of Materials Science and Engineering & Graduate School of
	Semiconductor Materials and Devices Engineering, Ulsan National Institute of
	Science and Technology, Ulsan 44919, Republic of Korea
	Direct deposition of high-k dielectrics on 2D-materials by ALD and its
	device applications (invited)
11.40-12.00	Li Zheng
11.40-12.00	State Key Laboratory of Materials for Integrated Circuits, Shanghai Institute of
	Microsystem and Information Technology, Chinese Academy of Sciences, Shanghai,
	200050
12:00-12:15	Oxidizer Engineering of ALD for Efficient Production of ZrO ₂ Capacitors
	in DRAM
	Xinyi Tang, Yuanbiao Li, Songming Miao, Xiao Chen, Guangwei Xu, Di Lu,
	Shibing Long
	University of Science and Technology of China, Hefei, 230026

	Saturday, October 19, 10:50 –12:15
Session B4	Meeting room B
Session Chair	: Prof. Han-Bo-Ram Lee
10:50-11:10	Surface reaction kinetics for Inherent Selective Atomic Layer Deposition of
	Tantalum oxide on Cu/SiO ₂ (invited)
	Cao kun
	School of Mechanical Science and Engineering, Huazhong University of Science and

	Technology, Wuhan, China, 430074
11.10 11.40	Surface adsorption/desorption reactions and precursor design for ALD/ALE
	(keynote)
11.10-11.40	Sang Ick Lee
	Semiconductor R&D Center, DNF Co. ltd.
	Advanced Atomic Level Patterning Process (invited)
11.40 12.00	Woo Hee Kim
11:40-12:00	Department of Materials Science and Chemical Engineering, Hanyang University,
	Korea
12:00-12:15	High Temperature TiN Atomic Layer Deposition using Various
	Nitrogenating Reactants
	Hyewon Park ¹ , Yoonseo Choi ¹ , and Han-Bo-Ram Lee ^{1*}
	Department of Materials Science and Engineering, Incheon National University,
	Incheon 2012, Republic of Korea

	Saturday, October 19, 10:50 –12:10
Session C4	Meeting room C
Session Chair: Prof. Hao Feng	
	Particle Atomic Layer Deposition for Battery Applications: From Liquid to
10.50 11.10	Solid-state (invited)
10.30-11.10	Ming Xie
	BattFlex (Wuhan) Technology Co., Ltd
	Revealing the mystery between Pt-Ti sites and exposed Pt sites in
	TiO _x -modified Pt catalyst
11:10-11:25	Huibin Ge ¹ , Yong Qin ²
	Interdisciplinary Research Center of Biology & Catalysis, School of Life Sciences,
	Northwestern Polytechnical University, Xi'an 710072, China
	Catalytically Ultrathin Titania Coating to Enhance Energy Storage and
	Release of Aluminum Hydride via Atomic Layer Deposition
11.25 11.40	Zhijia Hu, Xiao Liu*, and Rong Chen*
11:23-11:40	State Key Laboratory of Intelligent Manufacturing Equipment and Technology,
	School of Mechanical Science and Engineering, Huazhong University of Science and
	Technology, Wuhan 430074, Hubei, People's Republic of China
11:40-12:10	Atomic Scale Surface Modification of Nanomaterials for Electrochemical
	Applications (keynote)
	Se Hun Kwon
	School of Materials Science and Engineering, Pusan National University, Busan,
	46241, Republic of Korea

Saturday, October 19, 14:00–15:25		
Session A5	Meeting room A	
Session Chair	Session Chair: Prof. Yi Zhao	
	Plasma-Enhanced Atomic Layer Etching for Metal and Dielectric Materials	
	(keynote)	
14:00-14:30	Heeyeop Chae	
	School of Chemical Engineering, Sungkyunkwan University (SKKU), Suwon, 16419,	
	Korea	
	Ferroelectric AlScN integrated on Silicon (invited)	
14:30-14:50	Jiuren Zhou	
	Hangzhou Institute of Technology, Xidian University, Hangzhou, Zhejiang, 311200	
	Atomic layer etching of metals and metal oxides for semiconductor	
	applications (invited)	
14:50-15:10	Taewook Nam	
	Department of Semiconductor Systems Engineering, Sejong University, Seoul 05006,	
	South Korea	
	Effect of ozone pulse time on the IGZO film Characteristics deposited by	
15:10-15:25	thermal atomic layer deposition	
	Yongqing Shen, Jinjuan Xiang*, Zhengying Jiao, Liguo Chai, Yuting Chen, Guilei	
	Wang [*] , Chao Zhao	
	Beijing Superstring Academy of Memory Technology, Beijing, China, 100176	

Saturday, October 19, 14:00–15:25		
Session B5	Meeting room B	
Session Chair	Session Chair: Prof. Sang Ick Lee	
	Atomic Layer Deposition of Platinum Group Metals and Its Application	
	(invited)	
14:00-14:20	Minsu Kim	
	Department of Advanced Materials Engineering, Kyonggi University, Suwon,	
	Gyeonggi-do (Korea), 16227	
	Simulation of fluidization-atomic layer deposition of nanoparticle	
	agglomerates by CFD-DEM approach (invited)	
14:20-14:40	Daoyin Liu	
	Key Laboratory of Energy Thermal Conversion and Control of Ministry of	
	Education, Southeast University, Nanjing 210096, Jiangsu, China	
	Direct Processing by µDALP [™] . Precision Coatings for Next Gen Devices	
14:40-14:55	Masoud Akbari, Simone Santucci, Mira Baraket, Ivan Kundrata and Maksym	
	Plakhotnyuk*	
	Masoud Akbari, Simone Santucci, Mira Baraket, Ivan Kundrata and Maksym	
	Plakhotnyuk* ATLANT 3D, Taastrup, Denmark	
14:55-15:10	Nano to Micro: Or How to Combine ALD with PVD	
	Amit Sharma ¹ , Israel Ayala ¹ , Xavier Maeder ² , Carlos Guerra ¹	
	Swiss Cluster AG, Bahnhofstrasse 19, 3700 Spiez, Switzerland	

	Plasma-enhanced atomic layer deposited highly conductive niobium carbide
	thin films as next-generation diffusion barriers for Cu and Ru interconnects
15:10-15:25	Chaehyun Park ¹ , Minjeong Kweon, Sang Bok Kim, Soo-Hyun Kim*
	School of Semiconductor Materials and Devices Engineering, Ulsan National
	Institute of Science and Technology (UNIST), Ulsan 44919, Republic of Korea

Saturday, October 19, 14:00–15:30	
Session C5	Meeting room C
Session Chair	: Prof. Junjie Zhao
	Vapor phase deposition of conformal organic-inorganic hybrid films and
	their applications
14:00-14:15	Yixian Wang, Qingfeng Chang, Tuo Wang*, and Jinlong Gong
	School of Chemical Engineering and Technology, Tianjin University, Tianjin,
	300072
	Low-temperature crystallization of Hf _{0.5} Zr _{0.5} O ₂ thin films fabricated using
	H ₂ O ₂ as the ALD oxidant
14:15-14:30	Haoming Che1, Takashi Onaya1, Masaki Ishii2, Hiroshi Taka2, and Koji Kita1
	Department of Advanced Materials Science, The University of Tokyo, 5-1-5
	Kashiwanoha, Kashiwa, Chiba, Japan, 277-8561
	Molecular Layer Deposition of Conjugated Microporous Polymers for
	Molecular Separations (keynote)
14:30-15:00	Yong Wang
	School of Energy and Environment, Southeast University, Nanjing; College of
	Chemical Engineering, Nanjing Tech University, Nanjing 211816, P. R. China
	A theoretical study on the adsorption of Cp(CH ₃) ₅ Ti(OMe) ₃ as a precursor
	for TiN ALD
15:00-15:15	Jae Min Jang ¹ , Hye Won Park ² , Soo-Hyun Kim ³ , Han-Bo-Ram Lee ² ,
	and Bonggeun Shong ¹
	Chemical Engineering, Hongik University, Seoul, South Korea, 04066
	Shielding CO ₂ -Philic Sites in Trimmed Covalent Organic Framework Pores
	by Atomic Layer Deposition
15:15-15:30	Zhiwen Chen, ^[a,b] Ming Zhang, ^[a,b] Yubin Hu, ^[a,b] Yingwu Luo, ^[a] Zheng Yang, ^[b] Junjie
	Zhao ^{*[a,b]}
	State Key Laboratory of Chemical Engineering, College of Chemical and Biological
	Engineering, Zhejiang University 866 Yuhangtang Rd, Hangzhou 310058, China

Saturday, October 19, 15:50–17:15	
Session A6	Meeting room A
Session Chair: Prof. Heeyeop Chae	
	Atomic Layer Deposition of Hf _{1-x} Zr _x O ₂ Anti-ferroelectric Films for
	Advanced Memory Devices (Keynote)
15:50-16:20	Yi Zhao
	College of Information Science and Electronic Engineering, Zhejiang University,
	Hangzhou, Zhejiang, 310027
	ALD-based Memcapacitor for Efficient Computing (invited)
16:20-16:40	Zhigang Ji
	School of Integrated Circuits, Shanghai Jiaotong University, 200240
	Recent Advances in ALD of Mo-Based Electrodes for High-Performance
	DRAM Capacitors (invited)
16:40-17:00	Jeong Hwan Han
	Department of Materials Science and Engineering, Seoul National University of
	Science and Technology (Seoultech), Seoul 01811, Republic of Korea
17:00-17:15	Optimization and Application Study of the Device based on Hafnium oxide
	Ferroelectric Thin Films
	Li zhenhai ^{1*} , Li Qingxuan ¹ , and Chen lin ^{23*}
	School of integrated Circuits, Anhui University, Anhui 230601

Saturday, October 19, 15:50–17:15	
Session B6	Meeting room B
Session Chair: Prof. Jiaming Sun	
	Multi-Scale Fluidized Bed Reactor for Surface Coating and Modification of
	Powder-Based Materials (invited)
15:50-16:10	Hao Van Bui
	Faculty of Materials Science and Engineering, Phenikaa University, Hanoi 12116,
	Vietnam
	User experience of hollow cathode plasma-assisted atomic layer deposition
	for various thin films (invited)
16:10-16:30	Byung Joon Choi
	The Department of Materials Science and Engineering, Seoul National University of
	Science and Technology, Seoul 01811, Rep. of Korea
	Impact of application requirements on ALD tool design
16:30-16:45	Sami Sneck
	Beneq Oy, Olarinluoma 9, 02200 Espoo, Finland
16:45-17:00	High Performances of 3D Vertical Ferroelectric NAND FeFETs with HfLaO
	FE Layer and TiO ₂ -Channel
	Xujin Song, Shangze Li, Dijiang Sun, Chenxi Yu, Xiaoyan Liu, and Jinfeng Kang
	School of Integrated Circuits, Peking University, Beijing, 100871

17:00-17:15	Theoretical prediction on the configuration of hydroxyls on the surfaces of
	HfO ₂
	Sujin Kwon and Bonggeun Shong
	Chemical Engineering, Hongik University, Seoul, South Korea, 04066

	Saturday, October 19, 15:50–17:25
Session C6	Meeting room C
Session Chair	: Prof. Yong Wang
	Role of Atomic Layer Deposited ZnO in Confined Interfacial
	Synthesis of MOF Turing Patterns (invited)
15:50-16:10	Junjie Zhao
	College of Chemical & Biological Engineering, Zhejiang University, Hangzhou,
	China
	High-Temperature Atomic Layer Deposition of SiO ₂ using Metal-Organic Si
	Precursor
16.10-16.25	Sojeong Eom ¹ , Sanghun Lee ¹ , Seonyeong Park ¹ , Seunggyu Na ¹ , Jisang Yoo ¹ ,
10.10-10.25	Seung-min Jung ² , Hyungjun Kim ^{1*}
	School of Electrical and Electronic Engineering, Yonsei University, 50 Yonsei-Ro,
	Seodaemun-Gu, Seoul 03722, Korea
	ALD and Joule Heating-Induced Synthesis of High-Entropy Nano-Alloys for
	Enhanced Water Electrolysis Performance (keynote)
16:25-16:55	Kwan W. Tan
	School of Materials Science and Engineering, Nanyang Technological University,
	Singapore 639798
	Applications of atomic layer deposition in Perovskite Solar Cells
16:55-17:10	Weizhen Wang
	Shenzhen Yuansu Optoelectronics Technology CO LTD, Shenzhen
	Effects of Interlayer Formation by Oxidants and Substrates on Properties of
	ALD ZrO ₂ Thin Film
17:10-17:25	Seonyeong Park
	School of Electrical and Electronic Engineering, Yonsei University, Seodaemun-Gu,
	Seoul 03722, Korea

18:00	Banquet (Shanghai Ballroom)
18:00	Banquet (Shanghai Ballroom)

Sunday, October 20, 9:00–9:55	
Session A7	Meeting room A
Session Chair: Prof. Lin Chen	
	ALD-driven passivation layer for IGZO-based TFTs devices (invited)
09:00-09:20	Gang He
	School of Materials Science and Engineering, Anhui University, Hefei 230601, China
	Optoelectronic Artificial Synaptic Devices Based on ALD/MLD
	Inorganic-Organic Hybrid Thin Films (invited)
00.20 00.40	Aidong Li
09:20-09:40	National Laboratory of Solid State Microstructures, College of Engineering and
	Applied Sciences, Collaborative Innovation Center of Advanced Microstructures,
	Nanjing University, Nanjing 210093, P. R. China
	PEALD TiO ₂ -based FeFET Memory with Hf _{0.45} Zr _{0.55} O _x Ferroelectric Films
09:40-09:55	Wei Meng, Binbin Luo, Ze Shang, Ming Yang, Bao Zhu, Xiaohan Wu, Shi-Jin Ding*
	School of Microelectronics, Fudan University, Shanghai, 200433

Sunday, October 20, 9:00–9:55	
Session B7	Meeting room B
Session Chair: Prof. Seong-Yong Cho	
	Fabrication of Various Functional Optoelectronic Devices Utilizing Atomic
	Layer Deposition Technique (invited)
09:00-09:20	Duan Yu
	State Key Laboratory of Integrated Optoelectronics, College of Electronic Science and
	Engineering, Jilin University, Changchun 130012, China
	Electroluminescence from Rare Earth doped Gallium Oxide and Gallate
00.20 00.40	Films grown by Atomic Layer Deposition (invited)
09.20-09.40	Jiaming Sun
	School of Material Science and Engineering, Nankai University, City, Tianjin, 300350
	Plasma Enhanced Atomic Layer Deposition of SiO ₂ Thin Film for Efficient
09:40-09:55	Encapsulation of Organic Light-emitting Devices
	Zheng chen ^{1,2,} Yu Duan ^{1,2}
	College of Physics, Changchun University of Science and Technology, Changchun,
	Jilin Province

Sunday, October 20, 9:55–11:00	
Session A8	Meeting room A
Session Chair: Prof. Gang He	
	ALD Based Flexible Memristor for Low Power In-memory computing
00.55 10.15	(invited)
09.33-10.13	Tianyu Wang
	School of Integrated Circuits, Shandong University, Jinan 250100, China
	Atomic-Layer-Deposited InSnO Thin-Film Transistors with Scaled Channel
10.15 10.20	Length
10.13-10.30	Binbin Luo1 and Shi-jin Ding*
	School of Microelectronics, Fudan University, Shanghai 200433, China
	Fluorine-Treated Top-gate InAlZnO TFT for 2T0C DRAM with >1 ks
10.20 10.45	Retention Time at $V_{hold} = 0 V$
10:30-10:43	Linlong Yang1, Bao Zhu1, Xiaohan Wu1,2*, Shi-Jin Ding1,2*
	School of Microelectronics, Fudan University, Shanghai 200433, China
	First Demonstration of BEOL-Compatible InMgO Transistor by
10:45-11:00	Atomic-Layer-Deposited
	Ming Yang, Binbin Luo, Wei Meng , Bao Zhu, Xiaohan Wu, Shi-Jin Ding*
	School of Microelectronics, Fudan University, Shanghai, 200433

Sunday, October 20, 9:55–10:50	
Session B8	Meeting room B
Session Chair	: Prof. Yu Duan
	Atomic Layer Deposition Approaches for Future Emissive AR/VR
00.55 10.15	Applications (invited)
09.33-10.13	Seong-Yong Cho
	Dept. of Photonics and Nanoelectronics, Hanyang University, Ansan 15588, Korea
	Self-developed ALD Equipment and its Application in High Mobility
	IGZO-TFTs (invited)
10:15-10:35	Xinwei Ding
	Key Laboratory of Advanced Display and System Application, Ministry of Education,
	Shanghai University, Shanghai, 200072
	Low residual stress flexible thin film encapsulation of 2 mm bending radius
10:35-10:50	based on atomic layer deposition
	Guanran Wang, Yu Duan [*]
	Affiliation: Coll Elect Sci & Engn, State Key Lab Integrated Optoelect, Jilin Univ,
	Changchun, Jilin province, 130012

	Atomic-Scale Stress Modulation of Nanolaminate for Micro-LED
	Encapsulation
10.50 11.05	Di Wen, JiaCheng Hu, Ruige Ruan, Kun Cao, and Rong Chen*
10.30-11.03	State Key Laboratory of Intelligent Manufacturing Equipment and Technology, School
	of Mechanical Science and Engineering, Huazhong University of Science and
	Technology, Wuhan 430074, Hubei, People's Republic of China
11:05-11:20	Future of ultra-flexible thin film encapsulation of optoelectronic devices
	based on atomic layer deposition
	Yuhan Wang, Yu Duan*
	Affiliation: Coll Elect Sci & Engn, State Key Lab Integrated Optoelect, Jilin Univ,
	Changchun, Jilin province, 130012

Friday, October 18, 17:15-18:30	
Session Poster Shanghai Ballroom Anteroom	
	Atomic Layer Deposition of Aluminum-Molybdenum
	Oxide Films: Water and Waterless Processes
P01	Abay M. Maksumova, Ilmutdin M. Abdulagatov
	Department of Physical and Organic Chemistry, Dagestan State University, Makhachkala,
	Russian Federation, 367000
	Comparative Study on Lateral and Vertical Controlling of Atomic Arrangement
	in Multielement Oxides Grown by Atomic Layer Deposition; a Case Study of
	Dy-Doped HfO ₂
P02	Byung-ha Kwak, ¹ Ngoc Le Trinh ² , Wonjoong Kim ² , Han-Bo-Ram Lee ² and Il-kwon Oh ^{1,*}
	¹ Department of Intelligence Semiconductor Engineering, Ajou University, Suwon, Korea
	² Department of Materials Science and Engineering, Incheon National University, Incheon,
	Korea
	Investigating the ALD Deposition Mechanism of AlO _x Barriers in Relation to
	ODT Coverage
P03	Boxuan Li ¹ , Yanwei Wen ² , and Rong Chen
	¹ School of Materials Science and Engineering, ² School of Mechanical Science and
	Engineering, Huazhong University of Science and Technology, Hubei 430074, China.
	Voltage Shift Induced by Interfacial Dipole in the Dielectric Stack of
	Atomic-Layer Deposited Nb ₂ O ₅ Ultrathin Insertion Layer
D 04	Caiyu Shi ¹ , Lei Shen ¹ , Ziying Huang ¹ , Xinbin Ying ¹ , Xing Yu ¹ and Hongliang Lu ^{1*}
P04	Affiliation: State Key Laboratory of ASIC and System, Shanghai Institute of Intelligent
	Electronics & Systems, School of Microelectronics, Fudan University, Shanghai, 200433,
	China.
	Growth and Corrosion Resistance of Ultrathin Al ₂ O ₃ /TiO ₂ Films on
D05	Polydopamine-Modified Copper by Atomic Layer Deposition
P05	Chi Yan ¹ , Jialin Li ¹ , Haobo Wang ¹ , CuiLiu ¹ and Hongbo Li ¹
	East China University of Science and Technology, Shanghai, China, 200237.
	ALD Conformality Analysis Using Lateral High Aspect Ratio Test Structures
DOC	Feng Gao ¹ , Anish Philip ² , Jussi Kinnunen ¹ , Mikko Utriainen ¹
PUO	¹ Chipmetrics Ltd., Joensuu, Finland, 80130
	² Aalto University, School of Science and Technology, Espoo, Finland, 02150
	Analysis of Growth Rate and Consumption under the Impact of CVD caused by
	the Substrate Move in Spatial ALD
P07	Geng Ma ¹ , Fan Yang, Bin Shan, Rong Chen
	Affiliation: School of Mechanical Science and Engineering, Huazhong University of
	Science and Technology, Wuhan, Hubei, 430074

P08	ALD Combined with Super Hydrophobic Modification Enhancing the Water
	Vapor Barrier of PET for Photovoltaic
	Haobo Wang, Chi Yan, Chengyou Zhang, Hongbo Li and Cui Liu
	School of Materials Science and Engineering, East China University of Science and
	Technology, Shanghai, 200237
P09	Kinetic Monte Carlo Simulation of The Atomic Layer Deposition of Hafnium
	Oxide
	Haojie Li ¹ , Yanwei Wen ¹ , Bin Shan ¹ and Rong Chen ^{2,*}
	¹ School of Materials Science and Engineering, ² School of Mechanical Science and
	Engineering, Huazhong University of Science and Technology, Hubei 430074, China.
P10	Atomic Layer Deposition of Nanometric Metal Oxides for Corrosion Protection of
	Al Alloy Surfaces
	Jia-lin Li ¹ , Chi Yan ² , and Cui Liu
	East China University of Science and Technology, Shanghai, 200237
	Plasma Fluorination of ALD In ₂ O ₃ for Thin-Film Transistors with Remarkable
	Stability
D11	Jinxiong Li ¹ , Shanshan Ju ¹ , Songjie Yang ¹ , Xu Tian ¹ , Lei Lu ² , Shengdong Zhang ² , and
PII	Xinwei Wang ¹
	¹ School of Advanced Materials, Peking University, Shenzhen 518055, China
	² School of Electronic and Computer Engineering, Peking University, Shenzhen 518055, China
	Large Positive V _{FB} Shift in MOS Capacitors Achieved by The Insertion of Ga ₂ O ₃
	Dipole Layer
D13	Lei Shen ¹ , Xiao-Na Zhu ¹ , Yu-Chun Li ¹ , Cai-Yu Shi ¹ , Zi-Ying Huang ¹ , and Hong-Liang
F12	$Lu^{1,*}$
	¹ State Key Laboratory of ASIC and System, Shanghai Institute of Intelligent Electronics &
	Systems, School of Microelectronics, Fudan University, Shanghai 200433, China
P13	Construction of Amorphous Mesentropic Oxide Protective Layer-assisted Stable
	Zinc Metal Anode by ALD
	Liling Fu, Shuai Zhang, Shaozhong Chang, Ai-Dong Li*
	National Laboratory of Solid-State Microstructure, College of Engineering and Applied
	Sciences, Collaborative Innovation Center of Advanced Microstructures, Jiangsu Key
	Laboratory of Artificial Functional Materials, Nanjing University, 210093, P.R China
P14	Structural Optimization and Regulation of Ultrathin Bilayer Organic-Inorganic
	Hybrid Memristors by Molecular Layer Deposition
	Lin Zhu, Shuai Zhang, Chu-Yi Zhang, Ai-Dong Li*
	National Laboratory of Solid State Microstructures, Materials Science and Engineering
	Department, College of Engineering and Applied Sciences, Collaborative Innovation
	Center of Advanced Microstructures, Nanjing University, Nanjing 210093, P. R. China

	High-Barrier Ultrathin Bendable Nanolaminate Encapsulation with a 1.2 mm
	Bending Radius
P15	Ruige Yuan ¹ , Di Wen ² , Fan Yang* and Rong Chen*
	Affiliation: School of Mechanical Science and Engineering, Huazhong University of
	Science and Technology, Wuhan, China, 430074
	Optoelectronic Artificial Synapses Based on ZnO Nanoporous Hybrid Thin Films
	by ALD/MLD
P16	Song Sun, Shuai Zhang, Lin Zhu, and Ai-Dong Li*
	National Laboratory of Solid State Microstructures, College of Engineering and Applied
	Sciences, Nanjing University, Nanjing, Jiangsu Province, 210093
	Enhancing the Thermal Stability of Pt Nanoparticles by Constructing
	Island-isolated Configuration via Area Selective Atomic Layer Deposition
	Rongli Ye, Kun Cao*, and Rong Chen*
P1/	Affiliation: State Key Laboratory of Intelligent Manufacturing Equipment and Technology,
	School of Mechanical Science and Engineering, Huazhong University of Science and
	Technology, Wuhan 430074, Hubei, People's Republic of China
P18	Nanoscale Surface Strategies for Reducing Foulant Adhesion in Emulsion
	Polymerization
	Weiwei Du and Junjie Zhao
	State Key Laboratory of Chemical Engineering, College of Chemical and Biological
	Engineering, Zhejiang University, Hangzhou, China, 310058
P19	Inherently Atomic Layer Deposition of Oxides on Cu/SiO ₂ with Redox-Coupled
	Process
	Weizhen Wang, Kun Cao ¹ , Yicheng Li ¹ , Zilian Qi ¹ , Bin Shan ² and Rong Chen ¹
	Affiliation: School of Mechanical Science and Engineering, Huazhong University of
	Science and Technology, Wuhan, China, 430074
	Thermodynamic Modeling of the Processes of Molecular Layering of MoO ₃ on
P20	β -cristobalite and Monolayers of MoOx and AlO _x by the DFT method:
	Comparative Evaluation of the Reactions of MoOCl4, MoO2Cl2 and H2O
	S.G. Gadjimuradov ¹ , S.I. Suleymanov ² , I.M. Abdulagatov ¹ , A.I. Abdulagatov ¹
	¹ Dagestan State University, 43a M. Gadzhiyeva str., 367000, Makhachkala, Russia
	² Analytical Center for Collective Use of the Institute of Physics of the Dagestan Federal
	Research
	Center of the Russian Academy of Sciences, 45 M. Gadzhieva str., 367025, Makhachkala,
	Russia

P21	3D HfO ₂ -Based Capacitor with Superior Energy Storage Properties
	Yijun Zhang,*1 Wei Ren,*1 Gang Niu, 1 Zenghui Liu1 and Zuo-Guang Ye*2
	1 Electronic Materials Research Laboratory Key Laboratory of the Ministry of Education
	& International Center for Dielectric Research, School of Electronic Science and
	Engineering, Xi'an Jiaotong University, Xi'an, Shann Xi, 710049, China
	2 Department of Chemistry and 4D LABS Simon Fraser University Burnaby, BC V5A 1S6,
	Canada
P22	Improved Ferroelectric Properties in Ultra-Thin Ferroelectric Film Compatible
	with BEOL via ZrO ₂ Middle Layer Strategy
	Yinchi Liu ¹ , Hongliang Lu ¹ , Lin Chen ^{1, 2} , Shijin Ding ¹ and Wenjun Liu ^{1, 2, *}
	¹ School of Microelectronics, Fudan University, Shanghai, P. R. China, 200433
	² Zhangjiang Fudan International Innovation Center, Fudan University, Shanghai, P. R.
	China, 201203
	Atomic Layer Deposition for Surface Modification in Enhancing Electrocatalytic
	Oxygen Evolution Reaction
P73	Yue Huang, Shuai Zhang, Yu Liu, and Ai-Dong Li*
1 2 3	National Laboratory of Solid State Microstructures, Materials Science and Engineering
	Department, College of Engineering and Applied Sciences, Collaborative Innovation
	Center of Advanced Microstructures, Nanjing University, Nanjing 210093, P. R. China
	Atomic Layer Modulation (ALM) Process for Preparing Atomic-scale
	Homogeneous Alloy Thin Films
	Yeseul Son ¹ , Sang-Bok Kim ¹ , Debananda Mohapatra ¹ , Taehoon Cheon ² and Soo-Hyun
P24	Kim ^{1,*}
	¹ Graduate School of Semiconductor Materials and Devices Engineering, Ulsan National
	Institute of Science and Technology (UNIST), Ulsan 44919, Republic of Korea
	² Center of Core Research Facilities, Daegu 42988, Republic of Korea
P25	Efficiently Tuning the Electrical Performance of PBTTT-C14 Thin Film via in-situ
	Controllable Multiple Precursors (Al ₂ O ₃ :ZnO) Vapor Phase Infiltration
	Zhen Jia ¹ , Xueyang Mu ² , and Weike Wang [*]
	Affiliation: School of Materials Science and Engineering, Shaanxi University of Science &
	Technology, Xi'an, Shaanxi 710021, China
P26	Zirconium Carbide (ZrC _x) Thin Films Prepared by Plasma-Enhanced Atomic
	Layer Deposition as a Diffusion Barrier for Ru & Cu Metallization
	Minjeong Kweon ¹ , Chaehyun Park, Sang Bok Kim, and Soo-Hyun Kim*
	¹ Graduate School of Semiconductor Materials and Devices Engineering, Ulsan National
	Institute of Science and Technology (UNIST), Ulsan, Republic of Korea

P27	Ultra-Fast Hydrogen Detection with SnO ₂ /In ₂ O ₃ Thin Film Sensors Fabricated by
	Atomic Layer Deposition
	Shuai Zhang, Chen Wang, and Ai-Dong Li*
	National Laboratory of Solid State Microstructures, Materials Science and Engineering
	Department, College of Engineering and Applied Sciences, Collaborative Innovation
	Center of Advanced Microstructures, Nanjing University, Nanjing 210093, P. R. China
P28	3nm Thin In ₂ O ₃ Channel via different Precursor Recipe Comparison for Bottom
	Gate Thin Film Transistor
	Yan Xu ¹ , Xuewei Jiang ² , Fan Yang* and Rong Chen*
	School of Mechanical Science and Engineering, Huazhong University of Science and
	Technology, Wuhan 430074, China
P29	Scalable Deposition of SnO ₂ ETL via SALD for Large-Area Inverted Perovskite
	Solar Modules
	Xuewei Jiang, Bin Shan*, Fan Yang*, Rong Chen
	Affiliation: School of Materials Science and Engineering, Huazhong University of Science
	and Technology, Wuhan 430074, People's Republic of China; School of Mechanical
	Science and Engineering, Huazhong University of Science and Technology, Wuhan 430074,
	China
	Morphological evolution of atomic layer deposited hafnium oxide on aligned
	carbon nanotube arrays
P30	Sujuan Ding ¹ , Yifan Liu ² , Qian Shang ³ , Bing Gao ¹ , Fenfa Yao ¹ , Bo Wang ¹ , Xiaoming Ma ¹ , Zhiyong Zhang ² , Chuanhong Jin ¹ *
	¹ State Key Laboratory of Silicon and Advanced Semiconductor Materials, School of
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	² Key Laboratory for the Physics and Chemistry of Nanodevices and Center for
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